onsemi

MOSFET – N-Channel, POWERTRENCH[®]

20 V

FDG6335N

General Description

This N–Channel MOSFET has been designed specifically to improve the overall efficiency of DC–DC converters using either synchronous or conventional switching PWM controllers. It has been optimized use in small switching regulators, providing an extremely low $R_{DS(ON)}$ and gate charge (QG) in a small package.

Features

- 0.7 A, 20 V
 - $R_{DS(ON)} = 300 \text{ m}\Omega @ V_{GS} = 4.5 \text{ V}$
 - $R_{DS(ON)} = 400 \text{ m}\Omega @ V_{GS} = 2.5 \text{ V}$
- Low Gate Charge (1.1 nC Typical)
- High Performance Trench Technology for Extremely Low RDS(ON)
- Compact Industry Standard SC70-6 Surface Mount Package
- These Devices are Pb-Free and are RoHS Compliant

Applications

- DC-DC Converter
- Power Management
- Loadswitch

				-
Symbol	Parameter	Ratings	Units	
V _{DSS}	Drain-Source Voltage		20	V
V _{GSS}	Gate-Source Voltage		±12	V
۱ _D	Drain Current	Continuous (Note 1)	0.7	A
		Pulsed	2.1	
PD	Power Dissipation for Single Operation	(Note 1)	0.3	W
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

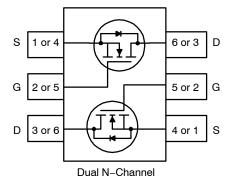
Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	415	°C/W

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design. $R_{\theta JA} = 415^{\circ}$ C/W when mounted on a minimum pad.



SC-88/SC70-6/SOT-363 CASE 419B-02

PIN CONNECTIONS



The pinouts are symmetrical; pin 1 and 4 are interchangeable

MARKING DIAGRAM



= Specific Device Code

35

Μ

= Assembly Operation Month

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FDG6335N

PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Reel Size	Tape Width	Shipping [†]
35	FDG6335N	7"	8 mm	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Мах	Unit
OFF CHARACT	ERISTICS					
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I _D = 250 μ A	20	-	-	V
$\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu\text{A}$, Referenced to 25°C	-	14	-	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 16 V, V_{GS} = 0 V	-	-	1	μΑ
I _{GSSF}	I_{GSSF} Gate-Body Leakage, Forward $V_{GS} = 12 \text{ V}, V_{DS} = 0 \text{ V}$		-	-	100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -12 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	-100	nA
ON CHARACTE	RISTICS (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	V_{DS} = V_{GS} , I_D = 250 μ A	0.6	1.1	1.5	V
$\Delta V_{GS(th)}$ / ΔT_J	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \ \mu A$, Referenced to $25^{\circ}C$	-	-2.8	-	mV/°C
R _{DS(on)}	Static Drain-Source On-Resistance	$ \begin{array}{l} V_{GS} = 4.5 \; V, \; I_D = 0.7 \; A \\ V_{GS} = 2.5 \; V, \; I_D = 0.6 \; A \\ V_{GS} = 4.5 \; V, \; I_D = 0.7 \; A, \; T_J = 125 ^{\circ} C \end{array} $	- - -	180 293 247	300 400 442	mΩ
I _{D(on)}	On-State Drain Current	V_{GS} = 4.5 V, V_{DS} = 5 V	1	-	-	А
9 _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 0.7 \text{ A}$	-	2.8	-	S
OYNAMIC CHAI	RACTERISTICS					
C _{iss}	Input Capacitance	V_{DS} = 10 V, V_{GS} = 0 V, f = 1.0 MHz	-	113	-	pF
C _{oss}	Output Capacitance		-	34	-	pF
C _{rss}	Reverse Transfer Capacitance		-	16	-	pF
SWITCHING CH	ARACTERISTICS (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ A},$	-	5	10	ns
t _r	Turn-On Rise Time	$V_{\rm GS}$ = 4.5 V, R _{GEN} = 6 Ω	-	7	15	ns
					1	-

t _r	Turn-On Rise Time	VGS - 4.0 V, HGEN - 0 12	-	7	15	ns
t _{d(off)}	Turn-Off Delay Time		-	9	18	ns
t _f	Turn-Off Fall Time		-	1.5	3	ns
Qg	Total Gate Charge	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 0.7 \text{ A}, V_{GS} = 4.5 \text{ V}$	-	1.1	1.4	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 4.5 V	-	0.24	-	nC
Q _{gd}	Gate-Drain Charge		-	0.3	-	nC

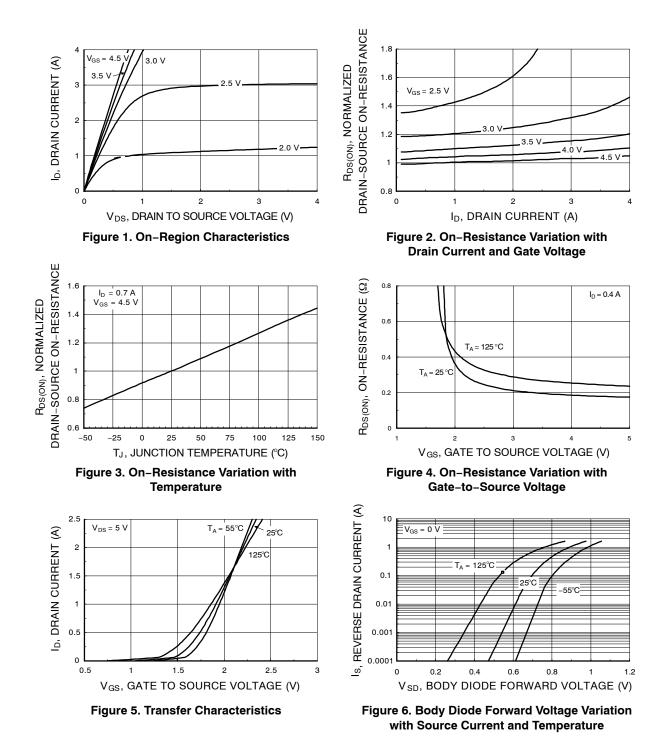
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

ا _S	Maximum Continuous Drain-Source Diode Forward Current		-	-	0.25	А
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 0.25 A (Note 2)	-	0.74	1.2	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width < 300 µs, Duty Cycle < 2.0%

FDG6335N

TYPICAL PERFORMANCE CHARACTERISTICS



FDG6335N

TYPICAL PERFORMANCE CHARACTERISTICS (CONTINUED)

10

8

6

4

2

0

0.001

0.01

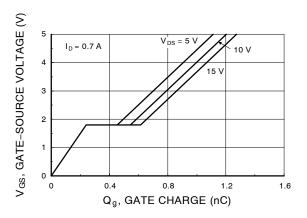


Figure 7. Gate Charge Characteristics

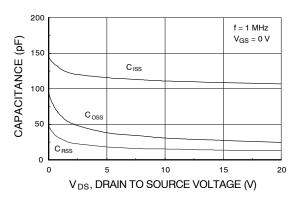


Figure 8. Capacitance Characteristics

SINGLE PULSE

R_{θJA} = 415°C/W

= 25°C

10

100

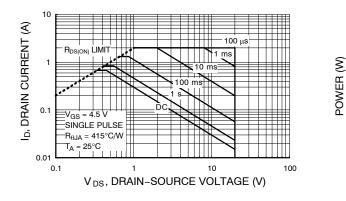
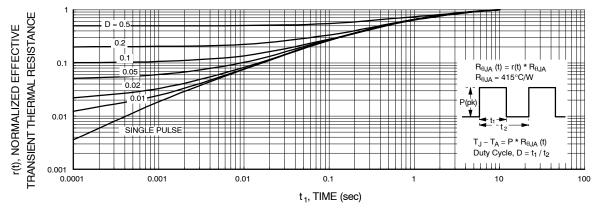


Figure 9. Maximum Safe Operating Area

t₁, TIME (sec) Figure 10. Single Pulse Maximum Power Dissipation

1

0.1



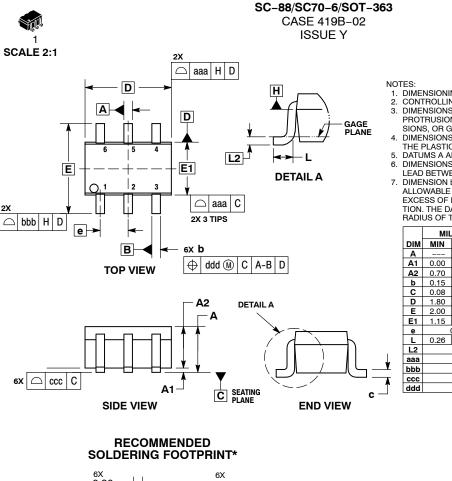
Thermal characterization performed using the conditions described in Note 1. Transient thermal response will change depending on the circuit board design.

Figure 11. Transient Thermal Response Curve

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DATE 11 DEC 2012



6X 0.30 0.66 2 50 0.65 PITCH DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. SIONS, OH GATE BUHHS SHALL NOT EXCEED 0.20 PEH END. DIMENSIONS D AND ET AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H. DATUMS A AND B ARE DETERMINED AT DATUM H. DIMENSIONS 5 AND 6 APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDI-TION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS				INCHES	3
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
Е	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е	(0.65 BS	С	0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			0.006 BSC		
aaa	0.15				0.006	
bbb	0.30				0.012	
ccc	0.10				0.004	
ddd		0.10			0.004	

GENERIC **MARKING DIAGRAM***



XXX = Specific Device Code

- Μ = Date Code*
- = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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SC-88/SC70-6/SOT-363 CASE 419B-02 ISSUE Y

DATE 11 DEC 2012

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13:	STYLE 14:	STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:
PIN 1. ANODE	PIN 1. VREF	PIN 1. ANODE 1	PIN 1. BASE 1	PIN 1. BASE 1	PIN 1. VIN1
2. N/C	2. GND	2. ANODE 2	2. EMITTER 2	2. EMITTER 1	2. VCC
3. COLLECTOR	3. GND	3. ANODE 3	3. COLLECTOR 2	3. COLLECTOR 2	3. VOUT2
4. EMITTER	4. IOUT	4. CATHODE 3	4. BASE 2	4. BASE 2	4. VIN2
5. BASE	5. VEN	5. CATHODE 2	5. EMITTER 1	5. EMITTER 2	5. GND
6. CATHODE	6. VCC	6. CATHODE 1	6. COLLECTOR 1	6. COLLECTOR 1	6. VOUT1
STYLE 19:	STYLE 20:	STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:
PIN 1. I OUT	PIN 1. COLLECTOR	PIN 1. ANODE 1	PIN 1. D1 (i)	PIN 1. Vn	PIN 1. CATHODE
2. GND	2. COLLECTOR	2. N/C	2. GND	2. CH1	2. ANODE
3. GND	3. BASE	3. ANODE 2	3. D2 (i)	3. Vp	3. CATHODE
4. V CC	4. EMITTER	4. CATHODE 2	4. D2 (c)	4. N/C	4. CATHODE
5. V EN	5. COLLECTOR	5. N/C	5. VBUS	5. CH2	5. CATHODE
6. V REF	6. COLLECTOR	6. CATHODE 1	6. D1 (c)	6. N/C	6. CATHODE
STYLE 25:	STYLE 26:	STYLE 27:	STYLE 28:	STYLE 29:	STYLE 30:
PIN 1. BASE 1	PIN 1. SOURCE 1	PIN 1. BASE 2	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. SOURCE 1
2. CATHODE	2. GATE 1	2. BASE 1	2. DRAIN	2. ANODE	2. DRAIN 2
3. COLLECTOR 2	3. DRAIN 2	3. COLLECTOR 1	3. GATE	3. COLLECTOR	3. DRAIN 2
4. BASE 2	4. SOURCE 2	4. EMITTER 1	4. SOURCE	4. EMITTER	4. SOURCE 2
5. EMITTER	5. GATE 2	5. EMITTER 2	5. DRAIN	5. BASE/ANODE	5. GATE 1
6. COLLECTOR 1	6. DRAIN 1	6. COLLECTOR 2	6. DRAIN	6. CATHODE	6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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